

Title (en)

METHOD FOR MAKING AN ORDERED POROUS STRUCTURE FROM AN ALUMINIUM SUBSTRATE

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER GEORDNETEN PORÖSEN STRUKTUR AUS EINEM ALUMINIUMSUBSTRAT

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE STRUCTURE POREUSE ORDONNÉE À PARTIR D'UN SUBSTRAT D'ALUMINIUM

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Application

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Abstract (en)

[origin: WO2009056744A2] The invention relates to a method for making a porous structure, that comprises producing, by anodisation of an aluminium substrate, an outer surface layer (3), part of the thickness of which is formed by an ordered porous structure (7), characterised in that it comprises an anodisation step on a smooth aluminium substrate for a duration sufficient for obtaining a thickness of ordered porous structure (7). The method further comprises removing by mechanical machining a portion of the thickness of said layer (3) formed by anodisation, said thickness portion extending from the outer surface of said layer (3) formed by anodisation, while maintaining an ordered porous structure (7) with a non-zero thickness, so that said ordered porous structure defines the free outer surface of the residual layer.

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